



IC Packages, Assembly & Prototype Services

# Press Release

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FOR IMMEDIATE RELEASE

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**GSA Suppliers Expo Provides Optimal Opportunity for the  
Semiconductor industry to View Innovative Solutions from Quik-  
Pak**

San Diego, CA, September 1, 2008 - Quik-Pak, a division of Delphon Industries, announced today that it will exhibit at the upcoming GSA Suppliers Expo October 2, 2008. The company plans on showing conference attendees its full turnkey solutions for their IC packaging and prototyping needs.

Quik-Pak, offers IC packages, assembly and prototype services. The company specializes in open-cavity plastic packages and assembly in 24 hours or less. A limitless array of open-cavity packages is available with no minimum quantity and can be provided as part of a turn-key assembly solution along with backgrinding, wafer dicing, die/wire bonding, remolding and marking/branding. Custom assembly services are also offered for

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ceramic packages, chip-on-board, stacked die, MEMS, etc. Quik-Pak's unique offerings deliver faster time to market and reduced prototype costs for new devices, while providing excellent flexibility, quality and customer service.

**For further information:**

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